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ELSP Electron. Signal Process.

Technique Report | Received 21 October 2024; Accepted 11 January 2025; Published 12 May 2025
https://doi.org/10.55092/20250003

Pinned-surface and double-junction photodiode type super high-performance image sensor with built-in solar cell structure

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Hagiwara YD, Electron. Signal Process. 2025(1):0003

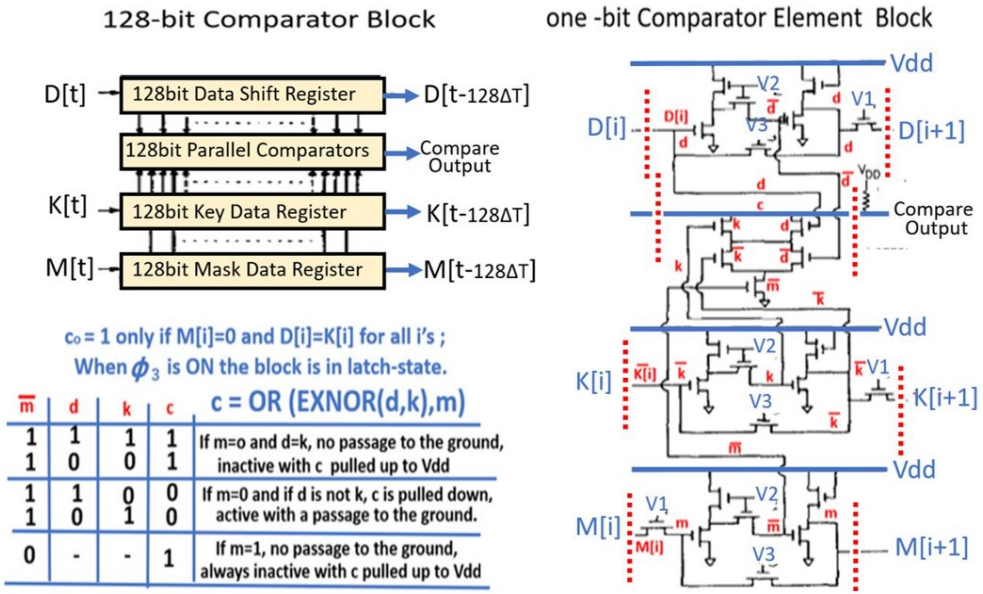

Figure 3. Full schematics of one bit slice of a new 128-bit multi-comparator for AI robot vision

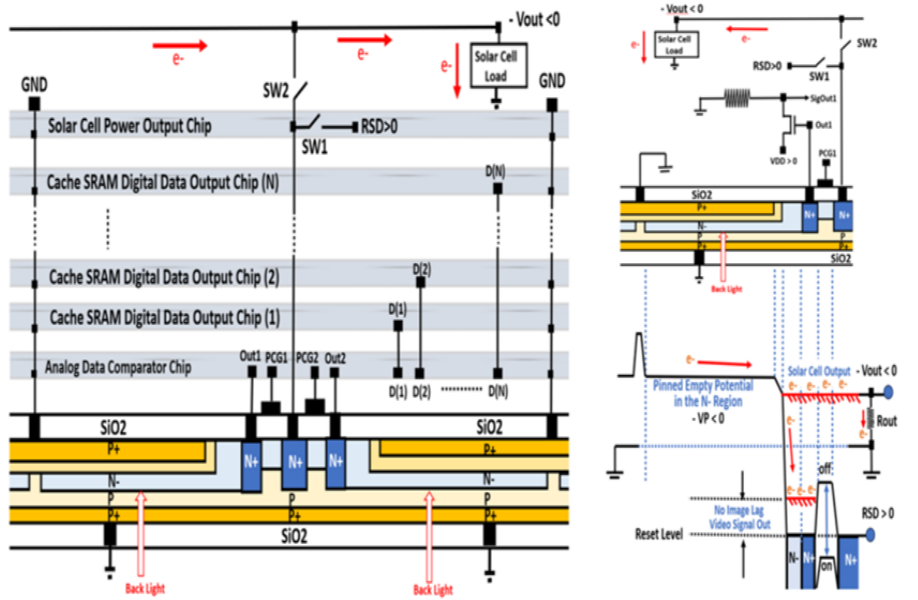

Figure 4. A cross-sectional view of a new AI Robot Vision chip in 3DIC multichip architecture

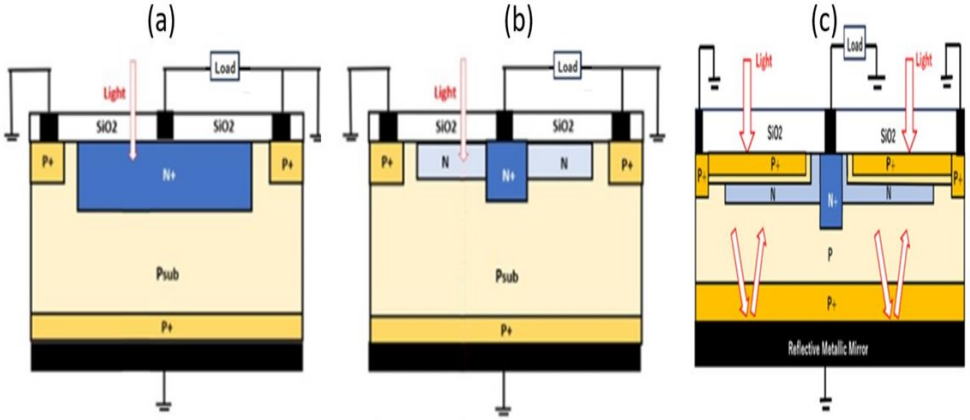

Figure 10. Two types of single junction photodiodes **(a)** and **(b)** with a double junction photodiode **(c)**.

The buried N region in Fig.10c is always completely depleted.